TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

TPC8112

TENTATIVE

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

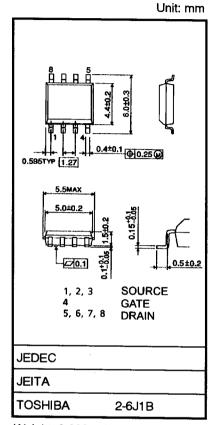
- · Small footprint due to small and thin package
- Low drain-source ON resistance: RDS (ON) = $5.0 \text{m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 31 \text{ S (typ.)}$
- Low leakage current: $IDSS = -10 \mu A (max) (VDS = -30 V)$
- Enhancement-mode: $V_{th} = -0.8 \text{ to } -2.0 \text{ V (V}_{DS} = -10 \text{ V}, I_D = -1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Character	istics	Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	-30	V
Drain-gate voltage (Ro	as = 20 kΩ)	V _{DGR}	-30	V
Gate-source voltage		V _{GSS}	±20	V
Drain current	DC (Note 1)	1 _D	-13	
Drain current	Pulse (Note 1)	I _{DP}	-52	A
Drain power dissipatio	n (t = 10 s) (Note 2a)	P _D	1.9	w
Drain power dissipatio	n (t = 10 s) (Note 2b)	P _D	1.0	w
Single pulse avalanche	e energy (Note 3)	E _{AS}	219	mJ
Avalanche current		IAR	-13	Α
Repetitive avalanche e	energy Note 2a) (Note 4)	E _{AR}	0.19	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55 to 150	°C

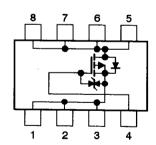
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

Circuit Configuration

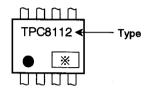


Thermal Characteristics

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Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

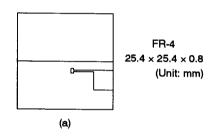
Marking (Note 5)

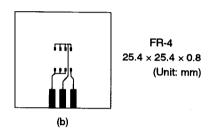


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

(a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)





Note 3: V_{DD} = -24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = -13 A

Note 4: Repetitive rating; pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

* shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

Electrical Characteristics (Ta = 25°C)

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Characteristics		Symboli	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		IGSS	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μА
Drain cut-OFF current		IDSS	V _{DS} = -30 V, V _{GS} = 0 V	_	-	-10	μА
Drain-source brea	kdown voltage	V (BR) DSS	I _D = -10 mA, V _{GS} = 0 V	-30	_	_	
Diam course brea		V (BR) DSX	I _D = -10 mA, V _{GS} = 20 V	- +1010 -30150.82.0 - 9.0 14 - 5.0 6.0 15.5 31 5880 1000 1050	٧		
Gate threshold vo	tage	V _{th}	V _{DS} = -10 V, I _D = -1 mA	-0.8	_	-2.0	V
Drain-source ON resistance		Pro (OLD	V _{GS} = -4 V, I _D = -6.5 A		9.0	14	mΩ
		R _{DS} (ON)	V _{GS} = -10 V, I _D = -6.5 A	_	5.0	6.0	
Forward transfer admittance		Y _{fs}	$V_{DS} = -10 \text{ V}, I_{D} = -6.5 \text{ A}$	15.5	31		S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz		5880	_	pF
Reverse transfer capacitance		C _{rss}			1000		
Output capacitance		Coss		_	1050	_	
Switching time	Rise time	t _r	V _{GS} = -6.5 A O V _{OUT} C C C C C C C C C C C C C C C C C C C	_	11		ns
	Turn-ON time	ton		-	22	_	
	Fall time	tf		_	110		
	Turn-OFF time	t _{off}		_	395		
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ -24 V, V _{GS} = 10 V, I _D = -13 A		130	_	nC
Gate-source charge 1		Q _{gs1}		_	10		
Gate-drain ("miller") charge		Q _{gd}		_	30		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	IDRP	_	_	_	-52	Α
Forward voltage (d	liode)		V _{DSF}	I _{DR} = -13 A, V _{GS} = 0 V			1.2	V

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